

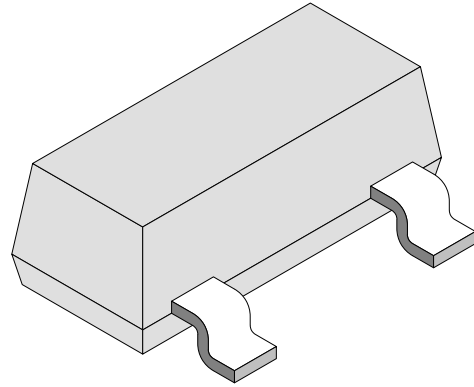
Silicon planar dual diode

Features

- Common anode

Applications

Fast switches in thick and thin film circuits



94 8550

Absolute Maximum Ratings

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Value	Unit
Reverse voltage			V_R	70	V
Peak forward surge current	$t_p=1\mu\text{s}$		I_{FSM}	4.5	A
Repetitive peak forward current			I_{FRM}	450	mA
Forward current	D1+D2		I_F	250	mA
Power dissipation			P_{tot}	300	mW
Junction temperature			T_j	150	$^\circ\text{C}$
Storage temperature range			T_{stg}	-55...+150	$^\circ\text{C}$

Maximum Thermal Resistance

$T_j = 25^\circ\text{C}$

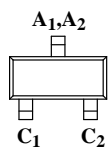
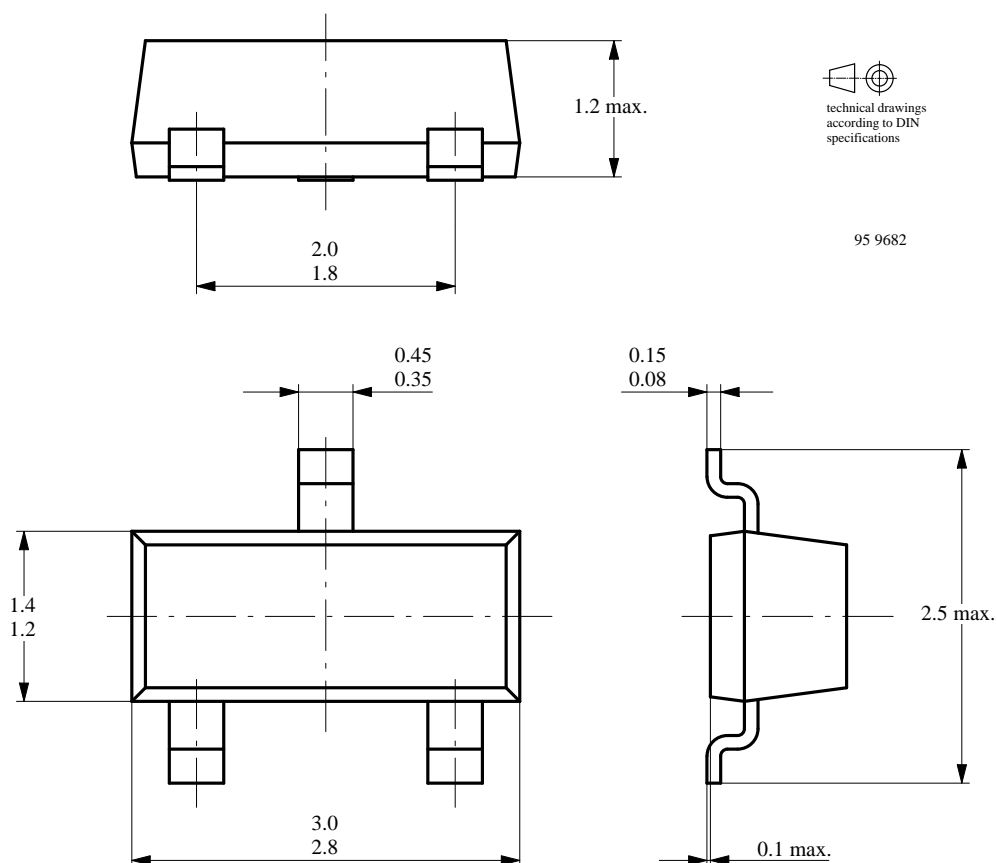
Parameter	Test Conditions	Symbol	Value	Unit
Junction ambient	on ceramic substrate 8mmx10mmx0.7mm	R_{thJA}	430	K/W

Characteristics

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Forward voltage	$I_F=1\text{mA}$		V_F			715	mV
	$I_F=10\text{mA}$		V_F			855	mV
	$I_F=50\text{mA}$		V_F			1	V
	$I_F=150\text{mA}$		V_F			1.25	V
Reverse current	$V_R=70\text{V}$		I_R			2.5	μA
	$V_R=70\text{V}, T_j=150^\circ\text{C}$		I_R			50	μA
	$V_R=25\text{V}, T_j=150^\circ\text{C}$		I_R			30	μA
Reverse recovery time	$I_F=10\text{mA}, I_R=10\text{mA}, i_R=1\text{mA}$		t_{rr}			6	ns
Diode capacitance	$V_R=0, f=1\text{MHz}$		C_D			1.5	pF

Dimensions in mm



Standard Plastic Case
23 A 3 DIN 41869/8
JEDEC TO 236
SOT 23

94 9542

OZONE DEPLETING SUBSTANCES POLICY STATEMENT

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

1. Meet all present and future national and international statutory requirements and
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

Of particular concern is the control or elimination of releases into the atmosphere of those substances which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) will soon severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of any ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA and
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with and do not contain ozone depleting substances.

We reserve the right to make changes to improve technical design without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

TEMIC TELEFUNKEN microelectronic GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany
Telephone: 49 (0)7131 67 2831, Fax Number: 49 (0)7131 67 2423